

DUAL DIGIT SMD DISPLAY(0.20")

# LSDD205/6DBK-XX

## DATA SHEET

DOC.NO : QW0905- LSDD205/6DBK-XX

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REV. : A

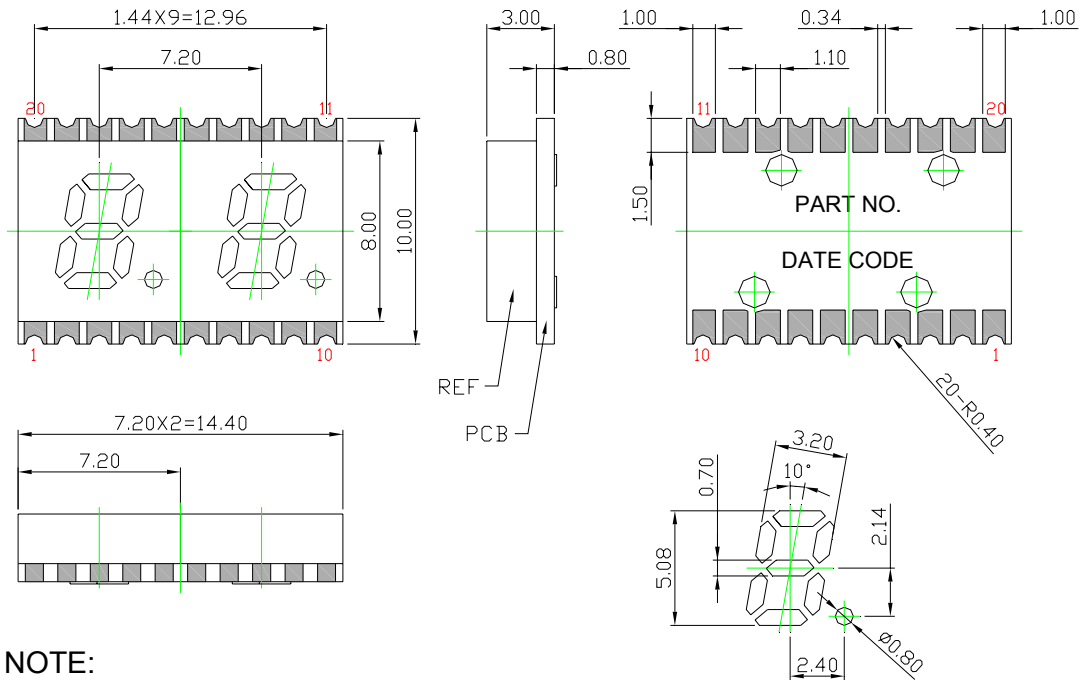
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DATE : 17 – May. – 2013

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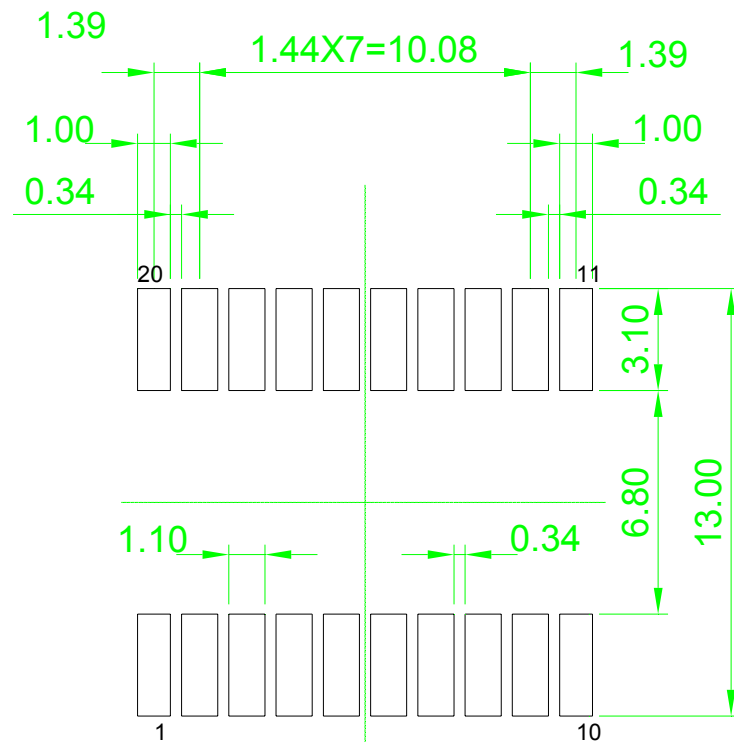


## Package Dimensions

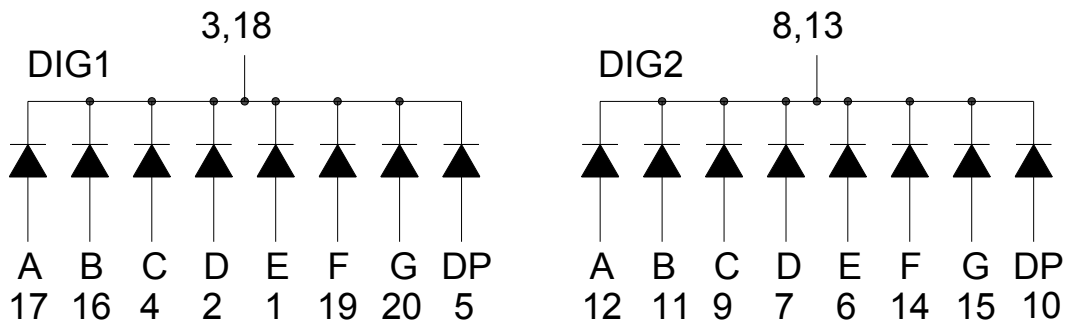
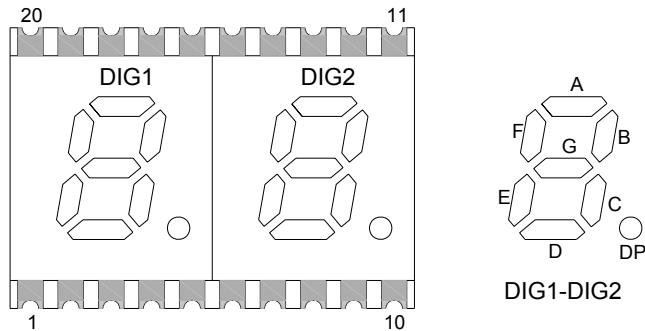


NOTE:  
Dimension in millimeter (inch),  
And tolerance is  $\pm 0.25$  (.01) specified.

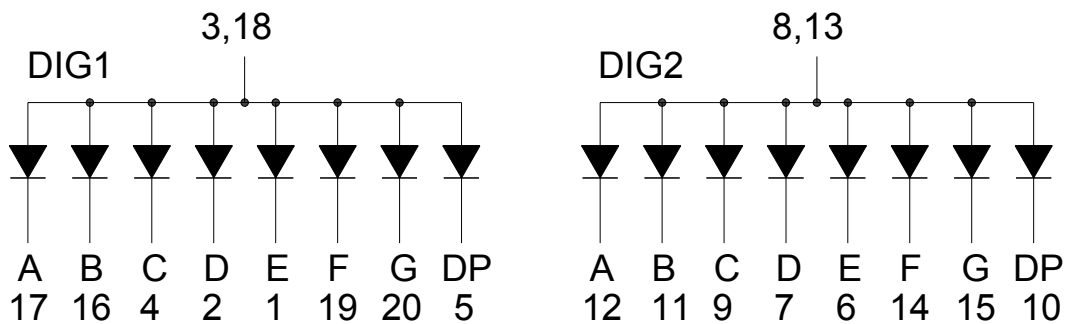
## Recommended Soldering Pad Dimensions



## Internal Circuit Diagram



LSDD205DBK-XX (Common Cathode)



LSDD206DBK-XX (Common Anode)

## Electrical Connection

PIN NO.	LSDD205DBK-XX	PIN NO.	LSDD206DBK-XX
1	Anode DIG1 E	1	Cathode DIG1 E
2	Anode DIG1 D	2	Cathode DIG1 D
3	Common Cathode DIG1	3	Common Anode DIG1
4	Anode DIG1 C	4	Cathode DIG1 C
5	Anode DIG1 DP	5	Cathode DIG1 DP
6	Anode DIG2 E	6	Cathode DIG2 E
7	Anode DIG2 D	7	Cathode DIG2 D
8	Common Cathode DIG2	8	Common Anode DIG2
9	Anode DIG2 C	9	Cathode DIG2 C
10	Anode DIG2 DP	10	Cathode DIG2 DP
11	Anode DIG2 B	11	Cathode DIG2 B
12	Anode DIG2 A	12	Cathode DIG2 A
13	Common Cathode DIG2	13	Common Anode DIG2
14	Anode DIG2 F	14	Cathode DIG2 F
15	Anode DIG2 G	15	Cathode DIG2 G
16	Anode DIG1 B	16	Cathode DIG1 B
17	Anode DIG1 A	17	Cathode DIG1 A
18	Common Cathode DIG1	18	Common Anode DIG1
19	Anode DIG1 F	19	Cathode DIG1 F
20	Anode DIG1 G	20	Cathode DIG1 G

## Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Ratings	UNIT
Power Dissipation	PD	120	mW
Peak pulse current Duty 1/10@10KHz	I <sub>FP</sub>	100	mA
Forward Current Per Chip	I <sub>F</sub>	30	mA
Debating liner from 25°C per segment	---	0.3	mA / °C
Storage Temperature	T <sub>stg</sub>	-40 ~ +105	°C
Operating Temperature	T <sub>opr</sub>	-40 ~ +105	°C

## Typical Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	IV	----	20		mcd	IF=20mA
Dominant Wavelength	λ D	----	470	-----	nm	IF=20mA
Spectral Line Half-Width	ΔP	----	30	----	nm	IF=20mA
Forward Voltage	VF	----	3.2	4.0	V	IF=20mA
Reverse Current	I <sub>r</sub>	----	----	10	μ A	VR=5V

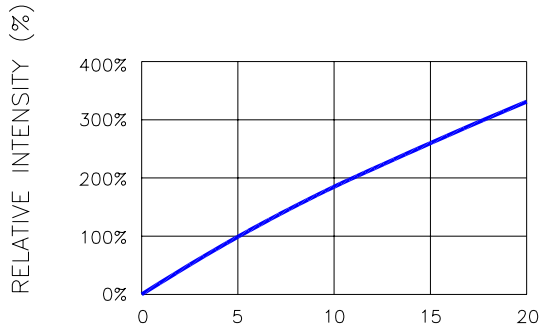
Note : 1.The forward voltage data did not including ±0.1V testing tolerance.

2.The luminous intensity data did not including ±15% testing tolerance.

## Typical Electro-Optical Characteristics Curve

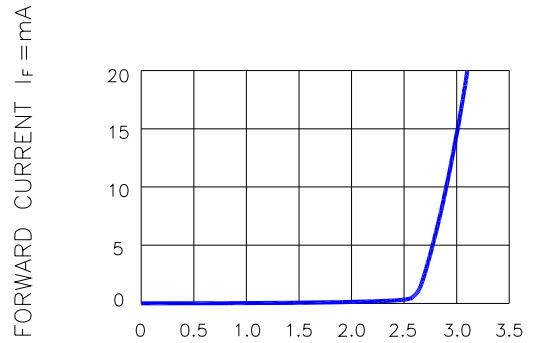
(25 °C Free Air Temperature Unless Otherwise Specified)

DBK: SUPER BRIGHT BLUE (InGaN) CURVE



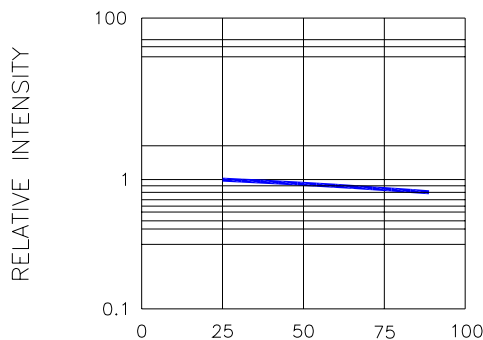
$I_f @ 20\text{mA}$  (mA)

Fig.1 RELATIVE INTENSITY VS. FORWARD CURRENT



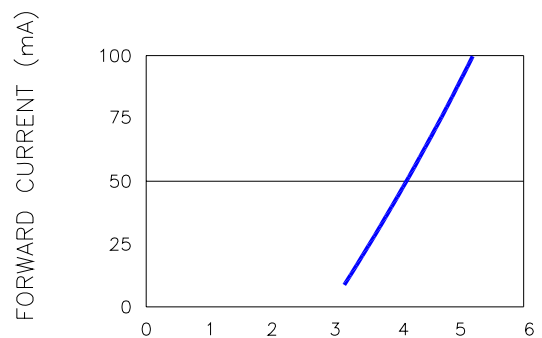
FORWARD VOLTAGE (V)

Fig.2 FORWARD CURRENT VS. FORWARD VOLT.



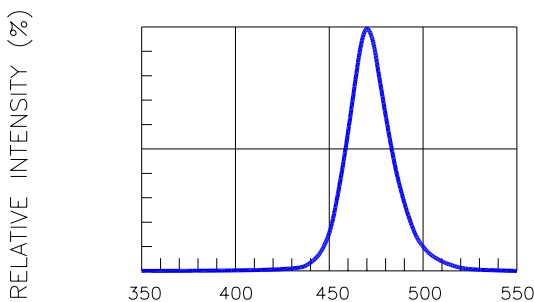
LEAD TEMPERATURE(°C)

Fig.3 RELATIVE INTENSITY VS.LEAD TEMPERATURE  
(PULSED 20 mA; 300us  
PULSE,10ms PERIOD)



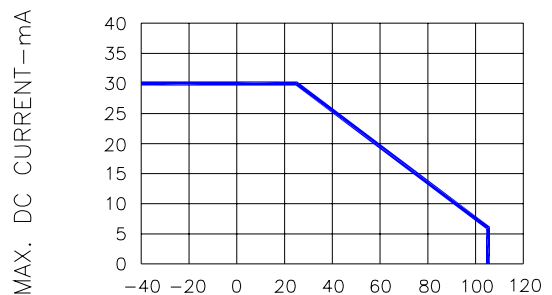
FORWARD VOLTAGE(V)

Fig.4 PEAK FORWARD VOLTAGE  
VS.FORWARD(100us TEST PULSE,  
1% DUTY CYCLE)



WAVELENGTH (nm)

Fig.5 RELATIVE INTENSITY VS. WAVELENGTH



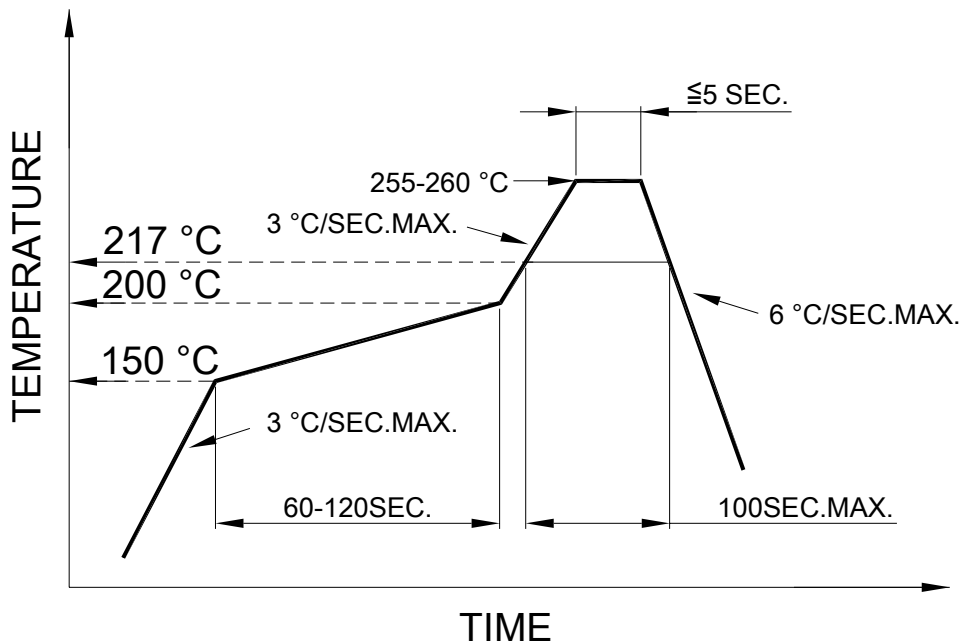
AMBIENT TEMPERATURE (TA)-°C

Fig.6 MAX. ALLOWABLE DC CURRENT  
VS. AMBIENT TEMPERATURE

## SMT REFLOW SOLDERING INSTRUCTIONS

SMT Soldering Profile

Pb free reflow soldering Profile



## SOLDERING IRON

Basic spec is  $\leq 4$  sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

## REWORK

Customer must finish rework within 3 sec. under 350°C.

The head of soldering iron cannot touch copper foil.